

SPECIFICATION**Features**

- Bidirectional I/O lines with a selection of 18, 22, 32, and 56 lines
- One interrupt input
- Programmable timer/event counters with overflow interrupts and with a selection of one 8-bit counter, one 8-bit and one 16-bit counters, and two 16-bit counters
- An on-chip crystal and an RC oscillator
- A watch dog timer
- A program ROM with a size selection of 1K×14 bits, 2K×14 bits, 4K×15 bits, and 8K×16 bits
- A data RAM with a size selection of 64×8 bits, 96×8 bits, 160×8 bits, and 224×8 bits
- Operating voltage: 2.4V~5.2V
- Halt function to reduce power consumption and wake-up feature
- 63 powerful instructions
- Up to 0.5μs instruction cycle with a 8MHz system clock at V_{DD}=5V
- All instructions in 1 or 2 machine cycles
- 14-bit/15-bit/16-bit table read instructions
- Two-level/four-level/eight-level subroutine nesting
- Bit manipulation instructions

General Description

The HT48C10/48C30/48C50/48C70 are 8-bit high performance RISC-like microcontrollers specifically designed for multiple I/O product applications. These devices are suitable for use in products such as remote controllers, fan/light controllers, washing machine controllers, scales, toys, and various subsystem controllers. They all contain a halt feature to reduce power consumption. The major differences between these microcontrollers are attributed to vari-

ations in sizes such as ROM and RAM as well as bit number, counter number, I/O line number, and different level subroutine nesting. Roughly speaking, the HT48C10 is a microcontroller with most economic facilities and the HT48C70 is one with most ample features of the four microcontrollers.

Selection Guide

Item	HT48C10	HT48C30	HT48C50	HT48C70
Operating Voltage	2.4~5.2	2.4~5.2	2.4~5.2	2.4~5.2
External Interrupt	1	1	1	1
Internal Interrupt	1	1	2	2
8-bit Timer/Event Counter	1	1	1	0
16-bit Timer/Event Counter	0	0	1	2
System Oscillator	Crystal/RC	Crystal/RC	Crystal/RC	Crystal/RC
Watchdog Timer	1	1	1	1
ROM	1K×14	2K×14	4K×15	8K×16
RAM	64×8 (40H~7FH)	96×8 (20H~7FH)	160×8 (60H~FFH)	224×8 (20H~FFH)
I/O Lines	18	22	32	56
Instructions	63	63	63	63
Stack Levels	2	2	4	8
Operating Frequency	400K~8MHz	400K~8MHz	400K~8MHz	400K~8MHz
OTP	HT48R10	HT48R30	HT48R50	HT48R70*
Power Down Mode	V	V	V	V
Table Read Instructions	V	V	V	V
Development System & OTP Writer	V	V	V	V

*: under development

The block diagram illustrates the internal architecture of the ATmega16 microcontroller. Key components include:

- Program Memory:** Program ROM and Program Counter.
- Instruction Path:** Instruction Register, Instruction Decoder, and Timing Generation (receiving OSC2 and OSC1 inputs).
- Stack:** STACK0 through STACK7, managed by the Program Counter.
- Interrupt System:** Interrupt Circuit (receiving INT input) and INTC (Interrupt Control and Status Register).
- Memory:** DATA Memory, connected to the system bus.
- Arithmetic and Logic:** ALU (Arithmetic Logic Unit) and Shifter, connected to the ACC (Accumulator).
- Timers and Counters:** TMR0, TMR0C, TMR1, TMR1C (16-bit timers), and WDT (Watchdog Timer) with WDT Prescaler.
- Ports:** PORT A through PORT G, each with corresponding data registers (PA, PB, PC, PD, PE, PF, PG) and pins (PA0-PA7, PB0-PB7, PC0-PC7, PD0-PD7, PE0-PE7, PF0-PF7, PG0-PG7).
- Other Features:** WDS (Watchdog Status Register), RC OSC (Reset Control Oscillator), and various multiplexers (MUX) for signal routing.

Pin Description HT48C10

Pin Name	I/O	Mask Option	Function
PA0~PA7	I/O	Wake-up pull high or none	Bidirectional 8-bit input/output ports Each bit can be configured as a wake-up input by mask option. Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
PB0~PB7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
VSS	—	—	Negative power supply, GND
$\overline{\text{INT}}$	I	—	External interrupt schmitt trigger input with a pull high resistor Edge triggered is activated on a high to low transition.
TMR	I	—	Schmitt trigger input for timer/event counter
PC0~PC1	I/O	Pull high or none	Bidirectional 2-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
$\overline{\text{RES}}$	I	—	Schmitt trigger reset input, active low
VDD	—	—	Positive power supply
OSC1 OSC2	I O	Crystal or RC	OSC1 and OSC2 are connected to an RC network or a crystal (by mask option) for the internal system clock. In the case of RC operation, OSC2 is the output terminal for 1/4 system clock.

Pin Description HT48C30

Pin Name	I/O	Mask Option	Function
PA0~PA7	I/O	Wake-up pull high or none	Bidirectional 8-bit input/output ports Each bit can be configured as a wake-up input by mask option. Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
PB0~PB7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
VSS	—	—	Negative power supply, GND
$\overline{\text{INT}}$	I	—	External interrupt schmitt trigger input with a pull high resistor Edge triggered is activated on a high to low transition.
TMR	I	—	Schmitt trigger input for timer/event counter
PC0~PC5	I/O	Pull high or none	Bidirectional 6-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
$\overline{\text{RES}}$	I	—	Schmitt trigger reset input, active low
VDD	—	—	Positive power supply
OSC1 OSC2	I O	Crystal or RC	OSC1 and OSC2 are connected to an RC network or a crystal (by mask option) for the internal system clock. In the case of RC operation, OSC2 is the output terminal for 1/4 system clock.

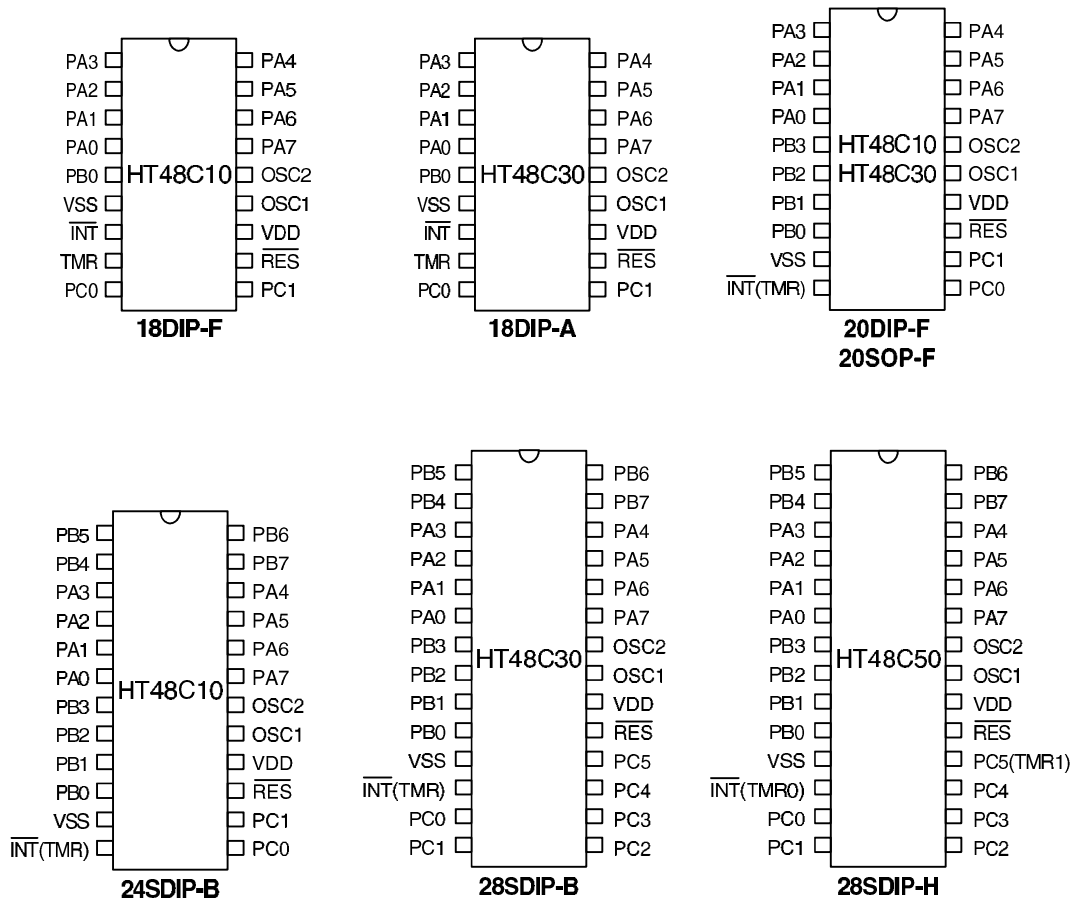
Pin Description HT48C50

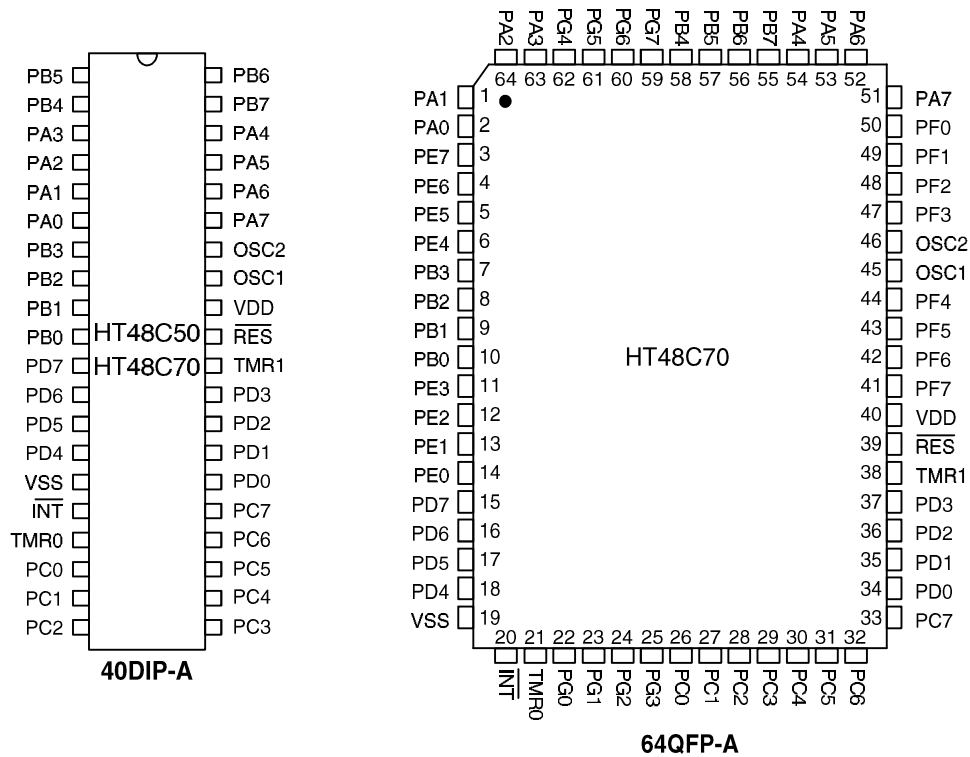
Pin Name	I/O	Mask Option	Function
PA0~PA7	I/O	Wake-up pull high or none	Bidirectional 8-bit input/output ports Each bit can be configured as a wake-up input by mask option. Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
PB0~PB7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
VSS	—	—	Negative power supply, GND
$\overline{\text{INT}}$	I	—	External interrupt schmitt trigger input with a pull high resistor Edge triggered is activated on a high to low transition.
TMR0	I	—	Schmitt trigger input for timer/event counter 0
TMR1	I	—	Schmitt trigger input for timer/event counter 1
PC0~PC7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
$\overline{\text{RES}}$	I	—	Schmitt trigger reset input, active low
VDD	—	—	Positive power supply
OSC1 OSC2	I O	Crystal or RC	OSC1 and OSC2 are connected to an RC network or a crystal (by mask option) for the internal system clock. In the case of RC operation, OSC2 is the output terminal for 1/4 system clock.
PD0~PD7	I/O	Pull high or none	Bidirectional 8-bit Input/Output port. Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).

Pin Description HT48C70

Pin Name	I/O	Mask Option	Function
PA0~PA7	I/O	Wake-up pull high or none	Bidirectional 8-bit input/output ports Each bit can be configured as a wake-up input by mask option. Software instructions determine the CMOS output or schmitt trigger input with or without a pull high resistor (by mask option).
PB0~PB7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
VSS	—	—	Negative power supply, GND
$\overline{\text{INT}}$	I	—	External interrupt schmitt trigger with a pull high resistor Edge triggered is activated on a high to low transition.
TMR0	I	—	Schmitt trigger input for timer/event counter 0
TMR1	I	—	Schmitt trigger input for timer/event counter 1
PC0~PC7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
$\overline{\text{RES}}$	I	—	Schmitt trigger reset input, active low
VDD	—	—	Positive power supply
OSC1 OSC2	I O	Crystal or RC	OSC1 and OSC2 are connected to an RC network or a crystal (by mask option) for the internal system clock. In the case of RC operation, OSC2 is the output terminal for 1/4 system clock.
PD0~PD7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
PE0~PE7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
PF0~PF7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).
PG0~PG7	I/O	Pull high or none	Bidirectional 8-bit input/output ports Software instructions determine the CMOS output or schmitt trigger input (pull-high depends on mask option).

Package & Pin Assignment



Package & Pin Assignment

Note:

1. Of the dice form, the TMR0 and TMR1 pads have to be bonded to VDD or VSS if the TMR0 and/or TMR1 pad are not used.
2. The (TMR0) $\overline{\text{INT}}$ indicates the TMR0 pad should be bonded to the $\overline{\text{INT}}$ pin.
3. The PC5 (TMR1) indicates the TMR1 pad should be bonded to the PC5 pin.

Absolute Maximum Ratings

(Ta=25°C)

Parameter	Symbol	Minimum	Maximum	Unit
Supply Voltage	V _{DD}	-0.3	5.5	V
Input Voltage	V _I	V _{SS} -0.3	V _{DD} +0.3	V
Storage Temperature	T _{STG}	-50	125	°C
Operating Temperature	T _{OP}	-25	70	°C

D.C. Characteristics

(Ta=25°C)

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
V _{DD}	Operating voltage	—	—	2.4	—	5.2	V
I _{DD1}	Operating current (HT48C10 Crystal OSC)	3V	No load f _{sys} =4MHz	—	0.7	1.5	mA
		5V		—	2	3	
I _{DD2}	Operating current (HT48C10 RC OSC)	3V	No load f _{sys} =2MHz	—	0.5	1	mA
		5V		—	1	2	
I _{DD3}	Operating current (HT48C30 Crystal OSC)	3V	No load f _{sys} =4MHz	—	0.7	1.5	mA
		5V		—	2	3	
I _{DD4}	Operating current (HT48C30 RC OSC)	3V	No load f _{sys} =2MHz	—	0.5	1	mA
		5V		—	1	2	
I _{DD5}	Operating current (HT48C50 Crystal OSC)	3V	No load f _{sys} =4MHz	—	1	2	mA
		5V		—	2.5	5	
I _{DD6}	Operating current (HT48C50 RC OSC)	3V	No load f _{sys} =2MHz	—	0.75	1.5	mA
		5V		—	1.5	3	
I _{DD7}	Operating current (HT48C70 Crystal OSC)	3V	No load f _{sys} =4MHz	—	1.5	3	mA
		5V		—	3.4	6	
I _{DD8}	Operating current (HT48C70 RC OSC)	3V	No load f _{sys} =2MHz	—	1	2	mA
		5V		—	2.1	4	

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
I _{STB1}	Standby current (WDT enabled)	3V	No load System HALT	—	—	5	μA
		5V		—	—	10	
I _{STB2}	Standby current (WDT disabled)	3V	No load System HALT	—	—	1	μA
		5V		—	—	2	
V _{IL}	Input low voltage for I/O ports	3V	—	0	—	0.9	V
		5V	—	0	—	1.5	
V _{IH}	Input high voltage for I/O ports	3V	—	2.1	—	3	V
		5V	—	3.5	—	5	
V _{IL1}	Input low voltage (TMR, TMR0, TMR1, INT)	3V	—	0	—	0.7	V
		5V	—	0	—	1.3	
V _{IH1}	Input high voltage (TMR, TMR0, TMR1, INT)	3V	—	2.3	—	3	V
		5V	—	3.8	—	5	
V _{IL2}	Input low voltage ($\overline{\text{RES}}$)	3V	—	—	1.5	—	V
		5V	—	—	2.5	—	
V _{IH2}	Input high voltage ($\overline{\text{RES}}$)	3V	—	—	2.4	—	V
		5V	—	—	4.0	—	
I _{OL}	I/O ports sink current	3V	V _{OL} =0.3V	1.5	4	—	mA
		5V	V _{OL} =0.5V	4	10	—	
I _{OH}	I/O ports source current	3V	V _{OH} =2.7V	−1	−2	—	mA
		5V	V _{OH} =4.5V	−2	−4.5	—	
R _{PH}	Pull-high resistance of I/O ports & INT	3V	—	40	60	80	kΩ
		5V	—	10	30	50	

A.C. Characteristics

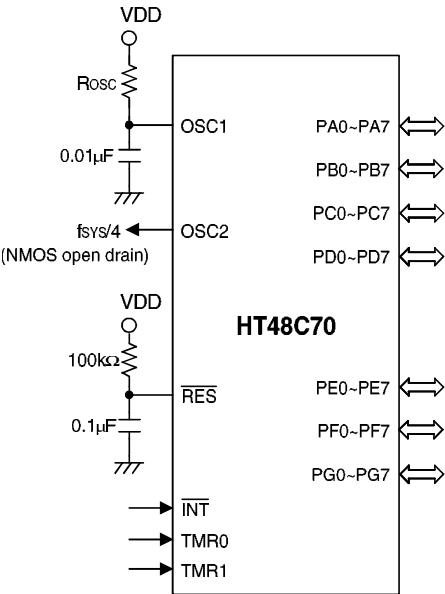
(Ta=25°C)

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V _{DD}	Conditions				
f _{SYS1}	System clock (Crystal OSC)	3V	—	400	—	4000	kHz
		5V	—	400	—	8000	
f _{SYS2}	System clock (RC OSC)	3V	—	400	—	2000	kHz
		5V	—	400	—	3000	
f _{TIMER}	Timer I/P frequency (TMR, TMR0, TMR1)	3V	—	0	—	4000	kHz
		5V	—	0	—	4000	
t _{WDTOSC}	Watchdog oscillator	—	—	45	90	180	μs
				35	65	130	
t _{WDT1}	Watchdog time-out period (RC)	—	Without WDT prescaler	12	23	45	ms
				9	17	35	
t _{WDT2}	Watchdog time-out period (System clock)	—	Without WDT prescaler	—	1024	—	t _{SYS}
t _{RES}	External reset low pulse width	—	—	1	—	—	μs
t _{SST}	System start-up timer period	—	Power-up or wake-up from halt	—	1024	—	t _{SYS}
t _{INT}	Interrupt pulse width	—	—	1	—	—	μs

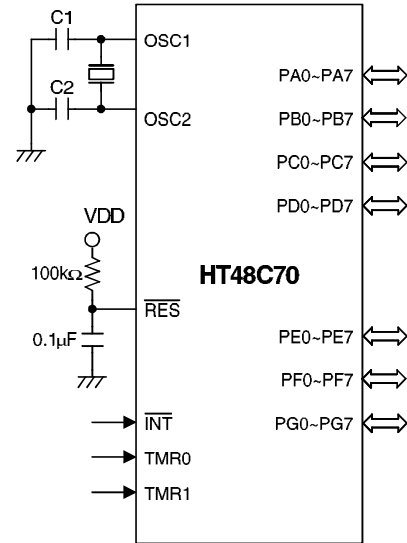
Note: t_{SYS}=1/(f_{SYS})

Application Diagram HT48C70

RC oscillator for multiple I/O applications



Crystal oscillator or ceramic resonator for multiple I/O applications



f _{sys} (kHz)	C1	C2	Crystal	Ceramic resonator
8000	0	0	OK	OK
6000	0	0	OK	OK
4000	0	0	OK	OK
3580	0	0	OK	OK
2000	0	0	OK	OK
1000	0	0	OK	—
640	300pF	300pF	—	OK
480	300pF	300pF	—	OK
455	300pF	300pF	—	OK
400	300pF	300pF	—	OK

SYSTEM ARCHITECTURE

The four microcontrollers of the HT48C10/HT48C30/HT48C50/HT48C70 are constructed basically using the same principles. Their differences lie in variations in sizes such as ROM and RAM as well as bit number, counter number, I/O line number, and different level subroutine nesting bit number. The following is a more detailed description of the system architectures of the four microcontrollers. Unless specified, the architecture stated below exists in these four microcontrollers.

Execution Flow

The system clock is derived from either a crystal or an RC oscillator. It is internally divided into four non-overlapping clocks. Each instruction cycle consists of four system clock cycles.

Instruction fetching and execution are pipelined in such a way that a fetch takes one instruction cycle while decoding and execution takes the next instruction cycle. The pipelining scheme causes each instruction to effectively execute in a cycle. If an instruction changes the program counter, two cycles are required to complete the instruction.

Program Counter - PC

The program counter (PC) is of different sizes ranging from 10 bits to 13 bits according to the microcontroller selected (10 bits for the HT48C10; 11 bits for the HT48C30; 12 bits for

the HT48C50; 13 bits for the HT48C70). It controls a sequence in which the instructions stored in the program ROM are executed. The content of the PC can specify 1024, 2048, 4096, or 8192 addresses maximum also according to the microcontroller (HT48C10/HT48C30/HT48C50/HT48C70) chosen.

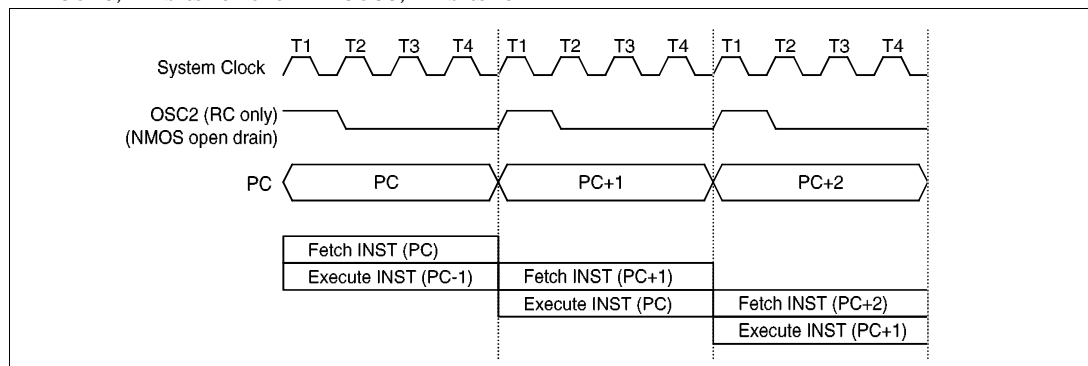
After accessing a program memory word in order to fetch an instruction code, the content of the PC is incremented by one. The PC then points to the memory word consisting of the next instruction code.

When executing a jump instruction, conditional skip execution, loading a PCL register, a subroutine call, an initial reset, an internal interrupt, an external interrupt, or returning from a subroutine, the PC manipulates a program transfer by loading the address corresponding to each instruction.

The conditional skip is activated by instructions. Once the condition is met, the next instruction, fetched during the current instruction execution, is discarded and a dummy cycle replaces it to get a proper instruction; otherwise proceed with the next instruction.

The lower byte of the PC (PCL) is a readable and writeable register (06H). Moving data into the PCL performs a short jump. The destination is within 256 locations.

Provided that a control transfer takes place, the execution will suffer from having an additional dummy cycle.



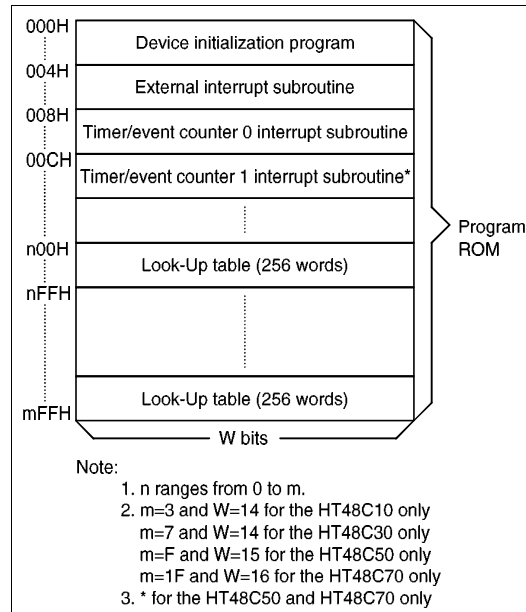
Execution Flow

Program Memory - ROM

The program memory (ROM) is used to store the program instructions that are to be executed. It contains data, table, and interrupt entries, and is organized with 1024×14 bits, 2048×14 bits, 4096×15 bits, or 8192×16 bits according to the microcontroller (HT48C10/HT48C30/HT48C50/HT48C70) selected. These bits are all addressed by the PC and table pointer.

Certain locations in the ROM stated below are reserved for special usage in the four microcontrollers except the location 00CH which is used for the HT48C50/HT48C70 exclusively.

- **Location 000H**
Location 000H is reserved for program initialization. After chip reset, the program always begins execution at this area.
- **Location 004H**
Location 004H is reserved for external interrupt service program. If the $\overline{\text{INT}}$ input pin is activated, the interrupt is enabled, and the stack is not full, the program begins execution at location 004H.
- **Location 008H**
Location 008H is reserved for the timer/event counter interrupt service program of the HT48C10/HT48C30 and for the timer/event counter 0 interrupt service pro-



Program Memory

gram of the HT48C50/HT48C70. If the timer interrupt results from a timer/event counter overflow of the HT48C10/HT48C30 or a timer/event counter 0 overflow of the HT48C50/HT48C70, and the interrupt is enabled, and the stack is not full, the program begins execution at location 008H.

Mode	Contents of Program Counter (m bits)
Initial reset	0000H
External interrupt	0004H
Timer/event Counter 0 overflow	0008H
Timer/event Counter 1 overflow	000CH
Skip	PC+2
Loading PCL	Low byte replaced by instruction code
Jump, call branch	Instruction code
Return from subroutine	Stack register

Notes: m=10 for the HT48C10
m=11 for the HT48C30
m=12 for the HT48C50
m=13 for the HT48C70

- **Location 00CH**
Location 00CH is reserved for the timer/event counter 1 interrupt service program of the HT48C50/HT48C70 only. If the timer interrupt results from a timer/event counter 1 overflow, the interrupt is enabled, and the stack is not full, the program begins execution at location 00CH.
- **Table location**
Any location in the ROM can be used as a look-up table. The instructions TABRDC [m] (the current page, 1 page=256 words) and TABRDL [m] (the last page) transfer the content of the lower-order byte to the specified data memory, and the higher-order byte to TBLH (08H). Only the destination of the lower-order byte in the table is well-defined, and the higher-order byte of the table word is transferred to the Table Higher-order byte register (TBLH). The TBLH is read only. The Table Pointer (TBLP), on the other hand, is a read/write register (07H) used to indicate the table location. Before accessing the table, the location should be placed in the TBLP. The TBLH is read only and cannot be re-stored. If the main routine and the ISR (Interrupt Service Routine) both employ the table read instruction, the content of the TBLH in the main routine is likely to be changed by the table read instruction used in the ISR. Errors are thus brought about. Given this, simultaneously using the table read instruction in the main routine and the ISR should be avoided. Nonetheless, if the

application of the table read instruction to both the main routine and the ISR cannot be avoided, interrupts are ought to be disabled prior to the table read instruction, and they will not be enabled until the TBLH is backup. All the table related instructions require 2 cycles to complete an operation. These areas may function as a normal program memory depending upon the user's requirements.

Stack Register - STACK

The stack register is a special part for memory that is used to save the content of the PC. The stack can be organized into 2 levels, 4 levels, or 8 levels according to the microcontroller elicited (2 levels for the HT48C10/HT48C30, 4 levels for the HT48C50, 8 levels for the HT48C70). The register is neither part of the data nor the program, and is neither readable nor writeable. Any activated level is indexed by a stack pointer (SP) and is neither readable nor writeable. At a subroutine call or interrupt acknowledgment, the content of the PC is pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction (RET or RETI), the content of the PC is restored to its previous value from the stack. After chip reset, the SP will point to the top of the stack.

If the stack is full and a non-masked interrupt takes place, the interrupt request flag is recorded but the acknowledgment is still inhibited. After

Instruction(s)	Table Location								
	*m~*8	*7	*6	*5	*4	*3	*2	*1	*0
TABRDC [m]	Pm~P8	@7	@6	@5	@4	@3	@2	@1	@0
TABRDL [m]	1~1	@7	@6	@5	@4	@3	@2	@1	@0

Table Location

Notes:

*m~*0: Bits of table location

@7~@0: Bits of table pointer

Pm~P8: Bits of current Program Counter

m=9 for the HT48C10

m=10 for the HT48C30

m=11 for the HT48C50

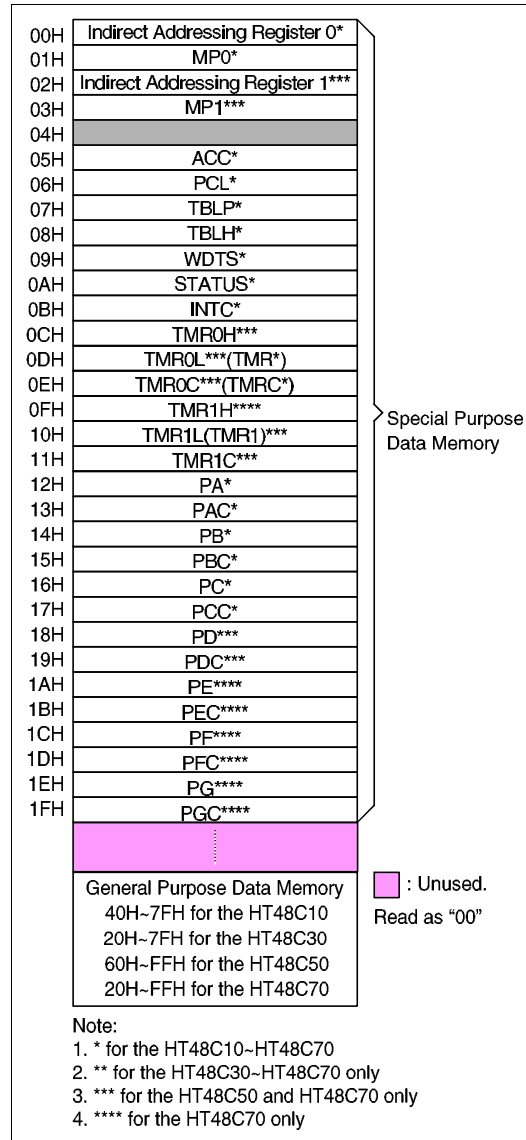
m=12 for the HT48C70

the stack pointer is decremented (by RET or RETI), the interrupt will be serviced. This feature prevents the occurrence of stack overflow allowing the programmer to use the structure easily. Likewise, if the stack is full and a CALL is subsequently executed, a stack overflow will occur and the first entry be lost (only the most recent four return address will be stored).

Data Memory - RAM

The data memory (RAM) composes of bits ranging from 81×8, 113×8, 184×8, or 255×8 according to the microcontroller chosen (HT48C10/HT48C30/HT48C50/HT48C70). It is divided into two functional groups, i.e., special function registers and general purpose data memory (of 64×8, 96×8, 160×8, or 224×8 bits according to the microcontroller selected (HT48C10/HT48C30/HT48C50/HT48C70). Most components of the two functional groups are readable/writable, but some are read-only.

Of the two functional groups, the special function registers in the four microcontrollers consist of a program counter lower-order byte register (PCL;06H), an accumulator (ACC;05H), a table pointer (TBLP;07H), a table higher-order byte register (TBLH;08H), a status register (STATUS;0AH), an interrupt control register (INTC;0BH), a watch dog timer option setting register (WDTS;09H), an indirect addressing register (00H), a memory pointer register (MP;01H), a timer/event counter (TMR;0DH), a timer/event counter control register (TMRC;0EH), I/O registers (PA;12H,PB;14H, PC;16H), and I/O control registers (PAC;13H,PBC;15H,PCC;17H). But of the HT48C50/HT48C70, the following components are further divided into two or several sub-components. First, the indirect addressing register is divided into two registers involving indirect addressing register 0 (00H) and indirect addressing register 1 (02H). Second, the memory pointer register is also comprised by two registers involving memory pointer register 0 (MP0;01H) and memory pointer register 1 (MP1;03H). Third, the timer/event counter register is organized by two registers according to different orders of byte, namely timer/event higher-order byte register and timer/event



RAM Mapping

lower-order byte register, both of which are further divided into timer/event counter 0 higher-order byte register (TMR0H; 0CH), timer/ event counter 1 higher-order byte register (TMR1H;0FH), timer/event counter 0 lower-order byte register (TMR0L;0DH), and timer/event counter 1 lower-order byte register (TMR1L;10H). Fourth, the timer/event counter control register is divided into two registers

involving timer/event counter 0 control register (TMR0C;0EH) and timer/event counter 1 control register (TMR1C;11H). Fifth, the entire number of I/O registers is expanded from 3 to 6 (PA;12H,PB;14H,PC;16H,PD;18H,PE;1AH,PF;1CH,PG;1EH). Finally, the number of I/O control registers is also doubled (PAC;13H,PBC;15H,PCC;17H,PDC;19H,PEC;1BH,PFC;1DH,PGC;1FH). The remaining space before the 20H of the four microcontrollers is all reserved for future expansion usage. Reading these remaining locations will return the result 00H. The general purpose data memory, addressed from 40H~7FH of the HT48C10, 20H~7FH of the HT48C30, 60H~FFH of the HT48C50, or 20H~FFH of the HT48C70 according to the microcontroller selected, is used for data and control information under instruction commands.

All the RAM areas can directly execute arithmetic, logic, increment, decrement, and rotate operations. Except some dedicated bits, each bit in the RAM can be set and reset by the SET [m].i and CLR [m].i instructions, respectively. These RAM areas are indirectly accessible through the memory pointer register(s) MP (01H) of the HT48C10/HT48C30 or MP0 (01H) and MP1 (03H) of the HT48C50/HT48C70.

Indirect Addressing Register

Of the four microcontrollers, the HT48C10/HT48C30 make use of location 00H whereas the HT48C50/HT48C70 of locations 00H and 02H as indirect addressing registers that are not physically implemented. Any read/write operation of [00H] or of [00H] and [02H] accesses the RAM pointed to by MP (01H) or by MP0 (01H) and MP1 (03H) respectively according to the microcontroller chosen. Reading location 00H or 02H indirectly will return the result 00H. Writing it indirectly will, on the other hand, result in no operation.

The function of data movement between two indirect addressing registers is not supported. The memory pointer register MP of the HT48C10/HT48C30 or MP0 and MP1 of the HT48C50/HT48C70 are of 7 bits or 8 bits wide respectively, and can be used to access the RAM

by combining according indirect addressing registers. The bit 7 of MP (HT48C10/HT48C30) is undefined and reading will return the result "1". Any writing operation to MP will only transfer the lower 7-bit data to MP.

Accumulator (ACC)

The accumulator (ACC) relates to the ALU operations. It is also mapped to location 05H of the RAM and is capable of operating with immediate data. The data movement between two data memory ought to get through the ACC.

Arithmetic and Logic Unit - ALU

This circuit performs 8-bit arithmetic and logic operations. It provides the following functions:

- Arithmetic operations (ADD, ADC, SUB, SBC, DAA)
- Logic operations (AND, OR, XOR, CPL)
- Rotation (RL, RR, RLC, RRC)
- Increment & Decrement (INC, DEC)
- Branch decision (SZ, SNZ, SIZ, SDZ, etc.)

The ALU can not only saves the results of data operation but change the status register.

Status Register - STATUS

The status register (0AH) is of 8 bits wide and consists of a zero flag (Z), a carry flag (C), an auxiliary carry flag (AC), an overflow flag (OV), a power down flag (PD), and a watch dog time-out flag (TO). The register also records the status information and controls the operation sequence.

Except the TO and PD flags, bits in the status register can all be altered by instructions, similar to the case with other registers. Any data written into the status register will not change the TO or PD flag. But the operations related to the status register may lead to different results from those intended. The TO and PD flags can be changed by system power up, Watch Dog Timer overflow, executing the HALT instruction, or clearing the Watch Dog Timer. The Z, OV, AC, and C flags all reflect the status of the latest operations.

On entering the interrupt sequence or executing the subroutine call, the status register will not be pushed onto the stack automatically. If the content of the status is important and the subroutine can corrupt the status register, the programmer should take precautions and save it properly.

Interrupt

The four microcontrollers all provide an external interrupt and internal timer/event counter interrupts. The interrupt control register (INTC;0BH) contains interrupt control bits for setting the enable/disable mode and the interrupt request flags.

Once an interrupt subroutine is serviced, the remaining interrupts will all be blocked (by clearing the EMI bit). This scheme may prevent any further interrupt nesting. Other interrupt requests may happen during this interval but only the interrupt request flag will be recorded. If a certain interrupt requires servicing within the service routine, the programmer may set the EMI bit and the corresponding bit of INTC so as to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even

if the related interrupt is enabled, until the SP is decremented. If immediate service is desired, the stack should be prevented from being full.

All these interrupts have a wake-up capability. As an interrupt is serviced, a control transfer occurs by pushing the PC onto the stack and then by branching it to subroutines at the specified location(s) in the ROM. Only the content of the PC can be pushed onto the stack. If the contents of the register and of the status register (STATUS) are altered by the interrupt service program which corrupts the desired control sequence, the programmer should save these contents first.

The external interrupt is triggered by a high to low transition of the $\overline{\text{INT}}$, and the related interrupt request flag (EIF; bit 4 of INTC) is then set. When the interrupt is enabled, the stack is not full, and the external interrupt is active, a subroutine call to location 04H will occur. The interrupt request flag (EIF) and EMI bits will also be cleared to disable other interrupts.

Of the four microcontrollers, the internal timer/event counter interrupt of the HT48C10/HT48C30 is initialized by setting the timer/event counter interrupt request flag (TF; bit 5

Labels	Bits	Function
C	0	C is set if the operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. Also it is affected by a rotate through the carry instruction.
AC	1	AC is set if the operation results in a carry out of the low nibbles in addition or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
Z	2	Z is set if the result of an arithmetic or of a logic operation is zero; otherwise Z is cleared.
OV	3	OV is set if the operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
PD	4	PD is cleared by either a system power-up or executing the CLR WDT instruction. PD is set by executing the HALT instruction.
TO	5	TO is cleared by a system power-up or executing the CLR WDT or HALT instruction. TO is set by a WDT time-out.
–	6	Undefined, read as 0
–	7	Undefined, read as 0

STATUS Register

of INTC), that is caused by a timer overflow. When the interrupt is enabled, and the stack is not full, and the TF bit is set, a subroutine call to location 08H will occur. The related interrupt request flag (TF) will be reset and the EMI bit be cleared to disable further interrupts.

As for the internal timer/event counter of the HT48C50/HT48C70, it composes of two interrupts, namely internal timer/event counter 0 interrupt and timer/event counter 1 interrupt. The internal timer/event counter 0 interrupt is initialized by setting the timer/event counter 0 interrupt request flag (T0F; bit 5 of INTC) which is caused by a timer/event counter 0 overflow. After the interrupt is enabled, the stack is not full, and the T0F bit is set, a subroutine call to location 08H will occur. The related interrupt request flag (T0F) will be reset and the EMI bit be cleared to disable further interrupts. On the other hand, the timer/event counter 1 interrupt is operated in the same manner as the timer/event counter 0. The related interrupt control bits ET1I and T1F of the timer/event counter 1 are bit 3 and bit 6 of the INTC, respectively.

During the execution of an interrupt subroutine of the four microcontrollers, other interrupt ac-

knowledgments are all held until the RETI instruction is executed or the EMI bit and the related interrupt control bit are both set to 1 (when the stack is not full). To return from the interrupt subroutine, the RET or RETI instruction may be invoked. The RETI will set the EMI bit in order to enable an interrupt service whereas the RET will not.

Interrupts that occur in an interval between the rising edges of two consecutive T2 pulses are serviced on the latter of the two T2 pulses if the corresponding interrupts are enabled. In the case of simultaneous requests the priority in the following table applies. That sequence can be masked by resetting the EMI bit.

No.	Interrupt Source	Priority	Vector
a	External interrupt	1	04H
b	Timer/event counter 0 overflow	2	08H
*c	Timer/event counter 1 overflow	3	0CH

* Note: No. c applies only to the HT48C50/ HT48C70.

Register	Bit No.	Label	Function
INTC (0BH)	0	EMI	Control the master (global) interrupt (1=enabled; 0=disabled)
	1	EEI	Control the external interrupt (1=enabled; 0=disabled)
	2	ET0I	Control the timer/event counter 0 interrupt (1=enabled; 0=disabled)
	3	ET1I	Control the timer/event counter 1 interrupt (for the HT48C50/HT48C70 only) (1=enabled; 0=disabled)
	4	EIF	External interrupt request flag (1=active; 0=inactive)
	5	T0F	Internal timer/event counter 0 request flag (1=active; 0=inactive)
	6	T1F	Internal timer/event counter 1 request flag (for the HT48C50/HT48C70 only) (1=active; 0=inactive)
	7	—	Unused bit, read as "0"

INTC Register

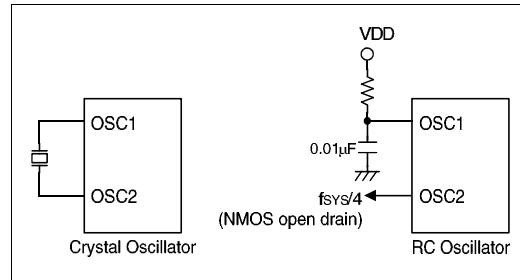
The timer/event counter interrupt request flag (TF), external interrupt request flag (EIF), enable timer/event counter bit (ETI), enable external interrupt bit (EEI), and enable master interrupt bit (EMI) constitute an interrupt control register (INTC) of the HT48C10/HT48C30 which is located at 0BH in the RAM. On the other hand, the timer/event counter 0/1 interrupt request flag (T0F/T1F), external interrupt request flag (EIF), enable timer/event counter 0/1 bit (ET0I/ET1I), enable external interrupt bit (EEI), and enable master interrupt bit (EMI) make up of the interrupt control register (INTC) of the HT48C50/HT48C70 which is located at 0BH in the RAM. EMI, EEI, and ETI, of the HT48C10/HT48C30 or EMI, EEI, ET0I, and ET1I of the HT48C50/HT48C70 are all used to control the enable/disable status of interrupts. These bits prevent the requested interrupt from being serviced. Once the interrupt request flags (TF, EIF of the HT48C10/HT48C30 or T0F, T1F, EIF of the HT48C50/HT48C70) are set, they will remain in the INTC register until the interrupts are all serviced or cleared by a software instruction.

It is suggested that a program not employ the "CALL subroutine" within the interrupt subroutine, since the operation of the "CALL subroutine" in the interrupt subroutine may damage the original control sequence, and interrupts often occur in an unpredictable manner or need to be immediately serviced in certain applications. Given this, if only one stack is left and enabling the interrupt is not well controlled, the original control sequence may be ruined as a result of operating the CALL subroutine in the interrupt subroutine.

Oscillator Configuration

There are 2 oscillator circuits available, namely RC oscillator and crystal oscillator, decided by mask options. Both are designed for system clocks. No matter what type of oscillator is chosen, the signal supports the system clock. The HALT mode ceases the system oscillator and resists external signals for conserving power.

Of the two oscillator types, if an RC oscillator is used, an external resistor between OSC1 and



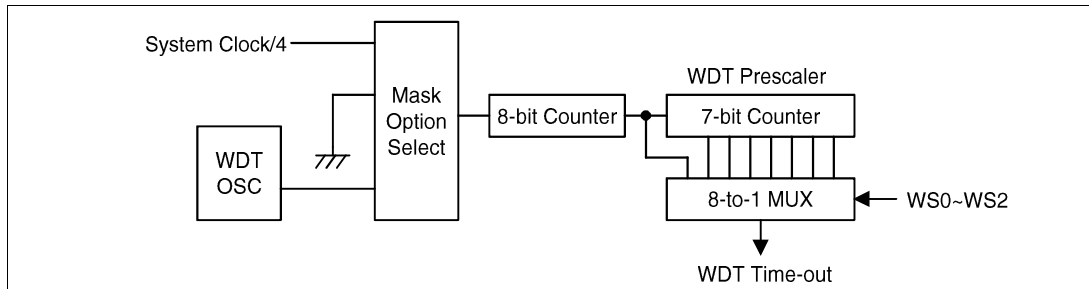
System Oscillator

VDD is required and its resistance ranges from 51kΩ to 1MΩ. The system clock, divided by 4, is available on OSC2 (NMOS open drain output), which can be used to synchronize external logic. The RC oscillator provides the most cost effective solution. However, the frequency of the oscillation may vary with VDD, temperature and the chip itself due to process variations. It is, therefore, not suitable for timing sensitive operations where accurate oscillator frequency is desired. On the other hand, if the crystal oscillator is used, a crystal across OSC1 and OSC2 is needed to provide the feedback and phase shift required for the crystal oscillator. No other external components are demanded. Instead of a crystal, the resonator can also be connected between OSC1 and OSC2 to derive a frequency reference, but two external capacitors in OSC1 and OSC2 are required.

The WDT oscillator is a free running on-chip RC oscillator, and no external components are required. Even if the system enters the power down mode, the system clock is ceased but the WDT oscillator still works with a period of approximately 78 μs. The WDT oscillator can be disabled by mask option to conserve power.

Watch Dog Timer - WDT

The clock source of the WDT is implemented by a dedicated RC oscillator (WDT oscillator) or an instruction clock (system clock divided by 4), decided by mask options. The WDT is designed to prevent a software malfunction or sequence from jumping to an unknown location with unpredictable results. The WDT can be disabled by mask option. If the WDT is disabled, all the executions related to the WDT may lead to no operation.



Watch Dog Timer

If the internal WDT oscillator (RC oscillator with a period of 78μs normally) is selected, it is first divided by 256 (8 stages) to derive a nominal time-out period of about 20ms. This time-out period may vary with temperature, VDD, and process variations. By invoking the WDT prescaler, longer time-out periods can be realized. Writing data to WS2, WS1, and WS0 (bit 2,1,0 of the WDTS) can lead to different time-out periods. If the values of WS2, WS1, and WS0 all equal to 1, the division ratio is up to 1:128, and the maximum time-out period is 2.6 seconds.

But if the WDT oscillator is disabled, the WDT clock may still come from the instruction clock and operate in the same manner except that in the HALT state the WDT may stop counting and lose its protecting purpose. In this situation the logic can be restarted by external logic. The high nibble and bit 3 of the WDTS are reserved for user defined flags, and the programmer may use these flags to indicate some specified status.

WS2	WS1	WS0	Division Ratio
0	0	0	1:1
0	0	1	1:2
0	1	0	1:4
0	1	1	1:8
1	0	0	1:16
1	0	1	1:32
1	1	0	1:64
1	1	1	1:128

WDTS Register

If the device operates in a noisy environment, using the on-chip RC oscillator (WDT OSC) is strongly recommended, since the HALT will terminate the system clock.

The overflow of WDT under normal operation can initialize “chip reset” and set the status bit TO. But in the HALT mode, the overflow will initialize a “warm reset”, and only the PC and SP are reset to zero. To clear the content of WDT (the WDT prescaler included), 3 methods can be adopted, i.e., external reset (a low level to RES), software instruction(s), and a HALT instruction. The software instruction(s) consists of CLR WDT and the other set — CLR WDT1 and CLR WDT2. Of these two types of instructions, only one type can be active depending on mask option — “CLR WDT times selection option”. If the “CLR WDT” is chosen (i.e., CLRWDT times equal one), any execution of the CLR WDT instruction will clear the WDT. In the case that the “CLR WDT1” and “CLR WDT2” are chosen (i.e., CLRWDT times equal two), these two instructions should be executed to clear the WDT; otherwise, the WDT may reset the chip due to time-out.

Power Down Operation - HALT

The HALT mode is initialized by the HALT instruction and results in the following.

- The system oscillator turns off but the WDT oscillator keeps running (If the WDT oscillator is selected).
- The contents of the on-chip RAM and of registers remain unchanged.
- The WDT and WDT prescaler are cleared and recount (if the clock of WDT comes from the WDT oscillator).

- All I/O ports maintain their original status.
 - The PD flag is set and the TO flag is cleared.
- The system can quit the HALT mode by external reset, an interrupt, an external falling edge signal on port A, or a WDT overflow. An external reset may cause device initialization, and the WDT overflow performs a “warm reset”. Examining the TO and PD flags, the reason for chip reset is determined. The PD flag is cleared by system power-up or executing the CLR WDT instruction, and is set by executing the HALT instruction. The TO flag is set if the WDT time-out occurs, and causes a wake-up that resets the PC and SP only. The others maintain their original status.

The port A wake-up and interrupt methods can be considered as a continuation of normal execution. Each bit in port A can be independently selected to wake up the device by mask option. Awakening from an I/O port stimulus, the program will resume execution of the next instruction. On the other hand, awakening from an interrupt, two sequences may happen. If the related interrupt(s) is disabled or the interrupt(s) is enabled but the stack is full, the program will resume execution at the next instruction. But if the interrupt is enabled and the stack is not full, the regular interrupt response takes place.

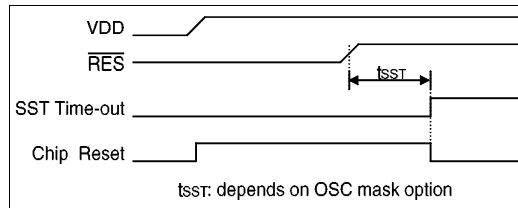
When wake-up event(s) occurs, it takes 1024 t_{sys} (system clock period) to resume normal operation. That is to say, a dummy period is inserted after the wake-up. If the wake-up results from an interrupt acknowledgment, the actual interrupt subroutine execution will be delayed by more than one cycle. But if the wake-up results in the next instruction execution, the instruction will execute immediately after the dummy period is finished. If an interrupt request flag is set to “1” before entering the HALT mode, the make-up function of the related interrupt will be disabled.

To minimize power consumption, all the I/O pins should be carefully managed before entering the HALT status.

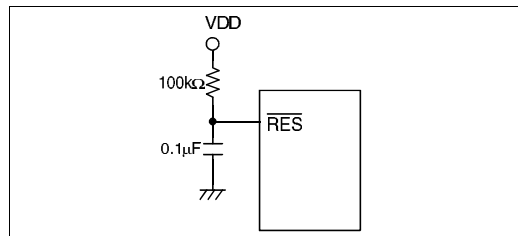
Reset

There are 3 ways in which reset may occur.

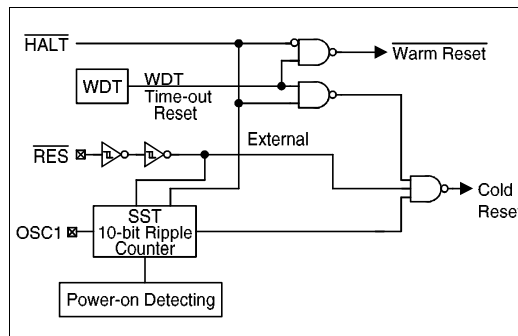
- \overline{RES} is reset during normal operation
 - \overline{RES} is reset during HALT
 - WDT timeout is reset during normal operation
- WDT time-out during the HALT is different from other chip reset conditions, for it can perform a “warm reset” that resets only PC and SP and leaves the other circuits at their original state. Some registers remain unchanged during any other reset conditions. Most of the registers are reset to the “initial condition” when the reset conditions are met. By examining the PD flag and TO flag, the program distinguishes between different “chip resets”.



Reset Timing Chart



Reset Circuit



Reset Configuration

TO	PD	RESET Conditions
0	0	$\overline{\text{RES}}$ reset during power-up
u	u	$\overline{\text{RES}}$ reset during normal operation
0	1	$\overline{\text{RES}}$ wake-up HALT
1	u	WDT time-out during normal operation
1	1	WDT wake-up HALT

Note: "u" means "unchanged".

To guarantee that the system oscillator is started and stabilized, the SST (System Start-up Timer) provides an extra-delay. The extra-delay delays 1024 system clock pulses when the system powers up or awakes from the HALT state.

When the system power-up occurs, the SST delay is added during the reset period. But when the reset comes from the RES pin, the SST delay is disabled. Any wake-up from HALT will enable the SST delay.

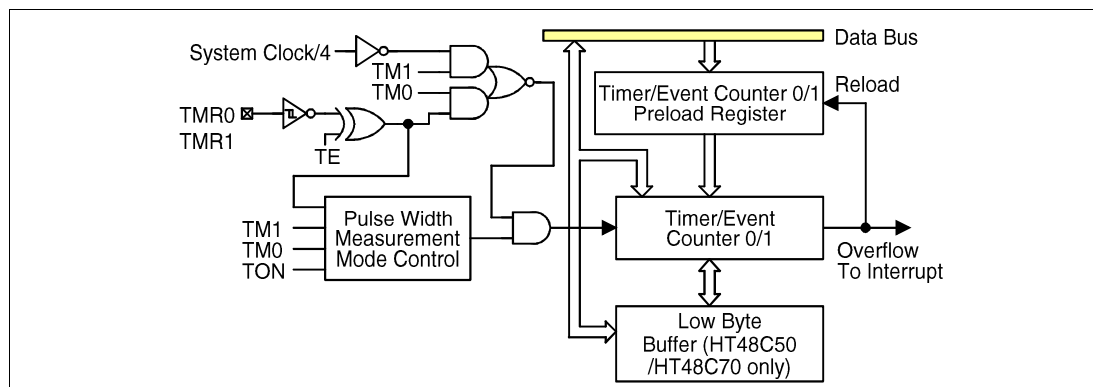
The status of the chip reset of the functional units are as shown.

PC	000H
Interrupt	Disabled
Prescaler	Cleared
WDT	Cleared After a master reset, WDT begins counting.

Timer/event Counter (0/1)	Off
Input/output Ports	Input mode
SP	Point to the top of the stack

Timer/Event Counter

There are two timer/event counters implemented in the four microcontrollers. Of the four microcontrollers, the timer/event counter of the HT48C10/HT48C30 contains an 8-bit programmable count-up counter. On the other hand, the timer/event counter of the HT48C50/HT48C70 composes of two counters, namely timer/event counter 0 and timer/event counter 1. The timer/event counter 0 contains a 16-bit programmable counter, and the timer/event counter 1 contains an 8-bit programmable count-up counter of the HT48C50. The timer/event counters 0 and 1 of the HT48C70 both contain a 16-bit programmable count-up counter. The source of the clock of the four microcontrollers may come from an external source or the system clock divided by 4. If the internal instruction clock is applied, only one reference time-base is available. The external clock input, on the other hand, allows the user to count external events, measure time intervals or pulse width, or generate an accurate time base.



Timer/Event Counter 0/1

The states of the special function registers are summarized in the following table:

Register	Reset (power on)	WDT time-out (normal operation)	RES reset (normal operation)	$\overline{\text{RES}}$ reset (HALT)	WDT time-out (HALT)
TMR1H	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TMR1L	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TMR1C	00-0 1---	00-0 1---	00-0 1---	00-0 1---	uu-u u---
TMR0H	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TMR0L	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TMR0C	00-0 1---	00-0 1---	00-0 1---	00-0 1---	uu-u u---
PC	000H	000H	000H	000H	000H*
MP0	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
MP1	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
TBLH	xxxx xxxx	uuuu uuuu	uuuu uuuu	uuuu uuuu	uuuu uuuu
STATUS	--00 xxxx	--1u uuuu	--uu uuuu	--01 uuuu	--11 uuuu
INTC	-000 0000	-000 0000	-000 0000	-000 0000	-uuu uuuu
WDTS	0000 0111	0000 0111	0000 0111	0000 0111	uuuu uuuu
PA	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PAC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PB	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PBC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PCC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PD	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PDC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PE	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PEC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PF	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PFC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PG	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu
PGC	1111 1111	1111 1111	1111 1111	1111 1111	uuuu uuuu

Note: “*” means “warm reset”.

“u” means “unchanged”.

“x” means “unknown”.

“–” means “undefined”

The bits of the special function registers are denoted as “–” if they are not defined in the microcontrollers.

Of the HT48C10/HT48C30, there are two registers related to the timer/event counter, i.e., TMR ([0DH]) and TMRC ([0EH]). There are two physical registers mapped to the TMR location. Writing TMR puts the starting value in the timer/event counter preload register while reading TMR gets the content of the timer/event counter. The TMRC, on the other hand, is a timer/event counter control register.

Of the HT48C50/HT48C70, the timer/event counter is comprised by 2 counters, i.e., timer/event counter 0 and timer/event counter 1. There are three registers related to the timer/event counter 0, namely TMR0H (0CH), TMR0L (0DH), and TMR0C (0EH). Writing TMR0L only writes the data into a low byte buffer, but writing TMR0H writes the data along with the content of the low byte buffer into the timer/event counter 0 preload register (16-bit). The timer/event counter 0 preload register is changed by writing the TMR0H operations, and writing TMR0L keeps the timer/event counter 0 preload register unaltered. Also, reading the TMR0H latches the TMR0L into the low byte buffer in order to avoid the false timing problem. Then, reading the TMR0L will return the content of the low byte buffer. In other words, the low byte of the timer/event counter 0 cannot be read directly. Instead it has to read the TMR0H first in order to make the low byte content of the timer/event

counter 0 latched into the buffer. On the other hand, there are also 3 registers related to the timer/event counter 1, namely TMR1H (0FH), TMR1L (10H), and TMR1C (11H). The timer/event counter 1 operates in the same manner as the timer/event counter 0.

The TMR0C is a timer/event counter 0 control register defining the timer/event counter 0 options. The timer/event counter 1 has the same options as the timer/event counter 0 and is defined by TMR1C.

The timer/event counter control registers of the four microcontrollers are all used to define the operation mode, counting enable or disable, and active edge.

The TM0 and TM1 bits define the operation mode. The event count mode is used to count external events, which means that the clock source comes from an external pin TMR of the HT48C10/HT48C30 or TMR0/TMR1 of the HT48C50/HT48C70. The timer mode functions as a normal timer with the clock source coming from the instruction clock. The pulse width measurement mode can be used to count the high or low level duration of the external signal TMR of the HT48C10/HT48C30 or TMR0/TMR 1 of the HT48C50/HT48C70. The counting is based on the instruction clock.

In the event count or timer mode, once the timer/event counter starts counting, it will count

Label	Bits	Function
–	0~2	Unused bits, read as “0”
TE	3	To define TMR0/TMR1 active edge of the timer/event counter (0=active on low to high; 1=active on high to low)
TON	4	To enable/disable timer counting (0=disabled; 1=enabled)
–	5	Unused bits, read as “0”
TM0 TM1	6 7	To define the operating mode 01=Event count mode (external clock) 10=Timer mode (internal clock) 11=Pulse width measurement mode 00=Unused

TMR0C/TMR1C Register

from the current content in the timer/event counter to FFH of the HT48C10/HT48C30/HT48C50 (TMR1) or to FFFFH of the HT48C50 (TMR0)/HT48C70. If an overflow occurs, the counter is reloaded from the timer/ event counter preload register and generates the corresponding interrupt request flag TF (bit 5 of INTC) of the HT48C10/HT48C30 or T0F/T1F (bit 5/6 of INTC) of the HT48C50/ HT48C70 at the same time.

In the pulse width measurement mode with the values of the TON and TE bits equal to one, if the TMR0/ TMR1 has received a transient from low to high (or high to low; if the TE bit is 0) it will start counting until the TMR of the HT48C10/HT48C30 or TMR0/TMR1 of the HT48C50/ HT48C70 returns to the original level and resets the TON. The measured result remains in the timer/event counter even if the activated transient happens again. In other words, only one cycle measurement can be done. Until setting the TON, the cycle measurement will re-function as long as it receives further transient pulse. In this operation mode, the timer/event counter starts counting according not to the logic level but to the transient edges. In the case of counter overflows, the counter is reloaded from the timer/event counter preload register and issues an interrupt request just like the other two modes.

To enable the counting operation, the timer ON bit (TON; bit 4 of TMRC of the HT48C10/ HT48C30 or bit 4 of TMR0C/TMR1C of the HT48C50/HT48C70) should be set to 1. In the pulse width measurement mode, the TON will be cleared automatically after the measurement cycle is complete. But in the other two modes the TON can only be reset by instructions. The overflow of the timer/event counter is one of the wake-up sources. No matter what the operation mode is, writing a 0 to ETI of the HT48C10/HT48C30 or to ET0I/ET1I of the HT48C50/HT48C70 can disable the corresponding interrupt service.

In the case of timer/event counter OFF condition, writing data to the timer/event counter preload register also reloads that data to the timer/event counter. But if the timer/event

counter is turned on, data written to the timer/event counter is reserved only in the timer/event counter preload register. The timer/event counter will go on operating until an overflow occurs.

After the timer/event counter (reading TMR of the HT48C10/HT48C30 or TMR0H/ TMR1H of the HT48C50/HT48C70) is read, the clock is blocked to avoid errors. As this may results in a counting error, blocking of the clock should be taken into account by the programmer.

Input/Output Ports

There are various numbers of bi-directional input/output lines in the four microcontrollers. The HT48C10 includes 18 bi-directional input/output lines, labeled from PA to PC, which are mapped to the [12H], [14H], or [16H] of the RAM, respectively. The HT48C30 contains 22 bi-directional input/output lines, labeled from PA to PC, which are mapped to [12H], [14H], or [16H], respectively. The HT48C50 consists of 32 bi-directional input/output lines, labeled from PA to PD, which are mapped to the [12H], [14H], [16H], or [18H], respectively. Finally, the HT48C70 contains 56 bi-directional input/output lines, labeled from PA to PG, which are mapped to the RAM of [12H], [14H], [16H], [18H], [1AH], [1CH], and [1EH], respectively. Of the four microcontrollers, all of these I/O ports can be used for input and output operations. For the input operation, these ports are non-latching, i.e., the inputs should be ready at the T2 rising edge of the instruction MOV A,[m] (m=12H, 14H, 16H, 18H, 1AH, 1CH, or 1EH). For the output operation, all data are latched and remain unchanged until the output latch is rewritten.

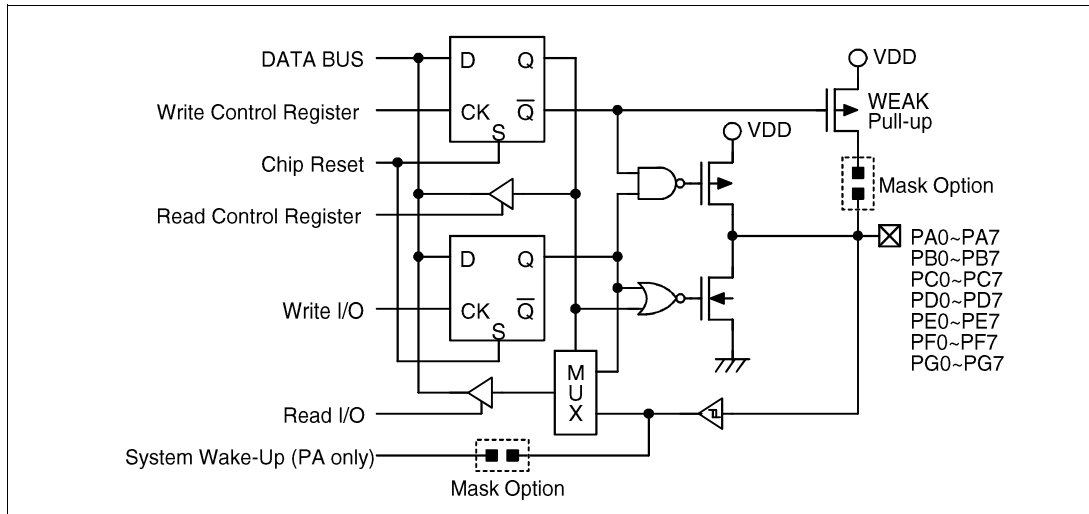
Each I/O line has its own control register (PAC, PBC, PCC, PDC, PEC, PFC, PGC (the first three registers PAC, PBC, PCC are all used by the four microcontrollers; the register PDC is extra-used by the HT48C50; all the 7 registers are applied in the HT48C70) to control the input/output configuration. With this control register, CMOS output or schmitt trigger input with or without pull-high resistor (by mask option)

structures can be reconfigured dynamically (i.e., on-the-fly) under software control. To function as an input, the corresponding latch of the control register must be written with "1". The pull-high resistance shows itself automatically if the pull-high option is selected. The input source(s) also depends on the control register. If the value of the control register bit is "1", the input will read the pad state. But if the value of the control register bit is "0", the contents of the latches will be moved to the internal bus. The latter is possible in "read-modify-write" instruction. For the output function, CMOS is the only configuration. These control registers are mapped to locations 13H, 15H, 17H, 19H, 1BH, 1DH and 1FH (the first three locations 13H, 15H, 17H exist in the four microcontrollers; the location 19H is used for the HT48C50; all the 7 locations are applied in the HT48C70).

After a chip reset, these input/output lines stay at the high level or floating (by mask option). Each bit of these input/output latches can be set or cleared by the SET [m].i or CLR [m].i (m=12H, 14H, 16H, 18H, 1AH, 1CH or 1EH (the first three options, namely 12H, 14H, and 16H, exist in the four microcontrollers; the HT48C50 is extra-provided with an option of 18H; these 7 options all exist in the HT48C70) instruction.

Some instructions first input data and then follow the output operations. For example, the SET [m].i, CLR [m].i, CPL [m] and CPLA [m] instructions read the entire port states into the CPU, execute the defined operations (bit-operation), and then write the results back to the latches or the accumulator.

Each line of port A has the capability to wake-up the device.



Input/Output Ports

Mask Option

The following table illustrates the 5 kinds of mask option provided. All these options have to be defined to ensure proper system functioning.

No.	Mask Option
1	OSC type selection. This option is to decide if an RC or Crystal oscillator is chosen as system clock. If the Crystal oscillator is selected, the XST (Crystal Start-up Timer) default is activated; otherwise the XST is disabled.
2	WDT source selection. There are 3 types of selection: on-chip RC oscillator, instruction clock or disable the WDT.
3	CLRWDT times selection. This option defines how to clear the WDT by instruction. "One time" means that the CLR WDT instruction can clear the WDT. "Two times" means only if both of the CLR WDT1 and CLR WDT2 instructions have been executed, the WDT can be cleared.
4	Wake-up selection. This option defines the activity of the wake-up function. External I/O pins (PA only) all have the capability to wake-up the chip from a HALT.
5	Pull-high selection. This option is to decide whether the pull-high resistance is viable or not in the input mode of the I/O ports. Each bit of the I/O port can be independently selected.

INSTRUCTION SET

Instruction Set Summary

Mnemonic	Description	Flag Affected	Instruction Cycle
Arithmetic			
ADD A,[m]	Add data memory to ACC	Z,C,AC,OV	1
ADDM A,[m]	Add ACC to data memory	Z,C,AC,OV	1 ⁽¹⁾
ADD A,x	Add immediate data to ACC	Z,C,AC,OV	1
ADC A,[m]	Add data memory to ACC with carry	Z,C,AC,OV	1
ADCM A,[m]	Add ACC to register with carry	Z,C,AC,OV	1 ⁽¹⁾
SUB A,x	Subtract immediate data from ACC	Z,C,AC,OV	1
SUB A,[m]	Subtract data memory from ACC	Z,C,AC,OV	1
SUBM A,[m]	Subtract data memory from ACC with result in data memory	Z,C,AC,OV	1 ⁽¹⁾
SBC A,[m]	Subtract data memory from ACC with carry	Z,C,AC,OV	1
SBCM A,[m]	Subtract data memory from ACC with carry with result in data memory	Z,C,AC,OV	1 ⁽¹⁾
DAA [m]	Decimal adjust ACC for addition with result in data memory	C	1 ⁽¹⁾
Logic Operation			
AND A,[m]	AND data memory to ACC	Z	1
OR A,[m]	OR data memory to ACC	Z	1
XOR A,[m]	Exclusive-OR data memory to ACC	Z	1
ANDM A,[m]	AND ACC to data memory	Z	1 ⁽¹⁾
ORM A,[m]	OR ACC to data memory	Z	1 ⁽¹⁾
XORM A,[m]	Exclusive-OR ACC to data memory	Z	1 ⁽¹⁾
AND A,x	AND immediate data to ACC	Z	1
OR A,x	OR immediate data to ACC	Z	1
XOR A,x	Exclusive-OR immediate data to ACC	Z	1
CPL [m]	Complement data memory	Z	1 ⁽¹⁾
CPLA [m]	Complement data memory with result in ACC	Z	1
Increment & Decrement			
INCA [m]	Increment data memory with result in ACC	Z	1
INC [m]	Increment data memory	Z	1 ⁽¹⁾
DECA [m]	Decrement data memory with result in ACC	Z	1
DEC [m]	Decrement data memory	Z	1 ⁽¹⁾

Mnemonic	Description	Flag Affected	Instruction Cycle
Rotate			
RRA [m]	Rotate data memory right with result in ACC	None	1
RR [m]	Rotate data memory right	None	1 ⁽¹⁾
RRCA [m]	Rotate data memory right through carry with result in ACC	C	1
RRC [m]	Rotate data memory right through carry	C	1 ⁽¹⁾
RLA [m]	Rotate data memory left with result in ACC	None	1
RL [m]	Rotate data memory left	None	1 ⁽¹⁾
RLCA [m]	Rotate data memory left through carry with result in ACC	C	1
RLC [m]	Rotate data memory left through carry	C	1 ⁽¹⁾
Data Move			
MOV A,[m]	Move data memory to ACC	None	1
MOV [m],A	Move ACC to data memory	None	1 ⁽¹⁾
MOV A,x	Move immediate data to ACC	None	1
Bit Operation			
CLR [m].i	Clear bit of data memory	None	1 ⁽¹⁾
SET [m].i	Set bit of data memory	None	1 ⁽¹⁾
Branch			
JMP addr	Jump unconditionally	None	2
SZ [m]	Skip if data memory is zero	None	1 ⁽²⁾
SZA [m]	Skip if data memory is zero with data movement to ACC	None	1 ⁽²⁾
SZ [m].i	Skip if bit i of data memory is zero	None	1 ⁽²⁾
SNZ [m].i	Skip if bit i of data memory is not zero	None	1 ⁽²⁾
SIZ [m]	Skip if increment data memory is zero	None	1 ⁽³⁾
SDZ [m]	Skip if decrement data memory is zero	None	1 ⁽³⁾
SIZA [m]	Skip if increment data memory is zero with result in ACC	None	1 ⁽²⁾
SDZA [m]	Skip if decrement data memory is zero with result in ACC	None	1 ⁽²⁾
CALL addr	Subroutine call	None	2
RET	Return from subroutine	None	2
RET A,x	Return from subroutine and load immediate data to ACC	None	2
RETI	Return from interrupt	None	2

Mnemonic	Description	Flag Affected	Instruction Cycle
Table Read			
TABRDC [m]	Read ROM code (current page) to data memory and TBLH	None	2 ⁽¹⁾
TABRDL [m]	Read ROM code (last page) to data memory and TBLH	None	2 ⁽¹⁾
Miscellaneous			
NOP	No operation	None	1
CLR [m]	Clear data memory	None	1 ⁽¹⁾
SET [m]	Set data memory	None	1 ⁽¹⁾
CLR WDT	Clear Watchdog timer	TO,PD	1
CLR WDT1	Pre-clear Watchdog timer	TO*,PD*	1
CLR WDT2	Pre-clear Watchdog timer	TO*,PD*	1
SWAP [m]	Swap nibbles of data memory	None	1 ⁽¹⁾
SWAPA [m]	Swap nibbles of data memory with result in ACC	None	1
HALT	Enter power down mode	TO,PD	1

Notes:

1. If a loading to PCL register occurs, the execution cycle of instructions will be delayed one more cycle (4 system clocks).
2. If a skipping next instruction occurs, the execution cycle of instructions will be delayed one more cycle (4 system clocks). Otherwise the original execution cycles remain unchanged.

3. 1 or 2

x = 8-bit immediate data

m = 7-bit data memory address for HT48C10/HT48C30

m = 8-bit data memory address for HT48C50/HT48C70

A = Accumulator

i = 0...7 number of bits

addr = Program memory address

√ = Flag(s) is affected

– = Flag(s) is not affected

* = Flag(s) may be affected by the execution status

Characteristic Curves

Figure A: Typical RC Oscillator frequency vs. Temperature

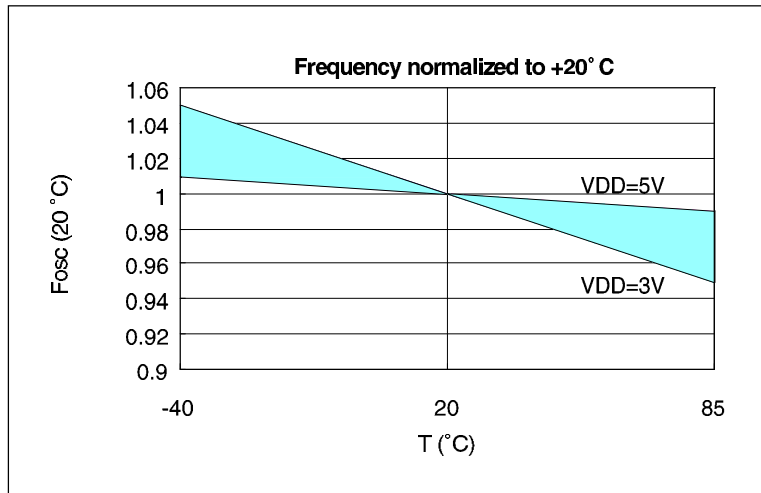


Figure B: Typical RC Oscillator frequency vs. V_{DD}

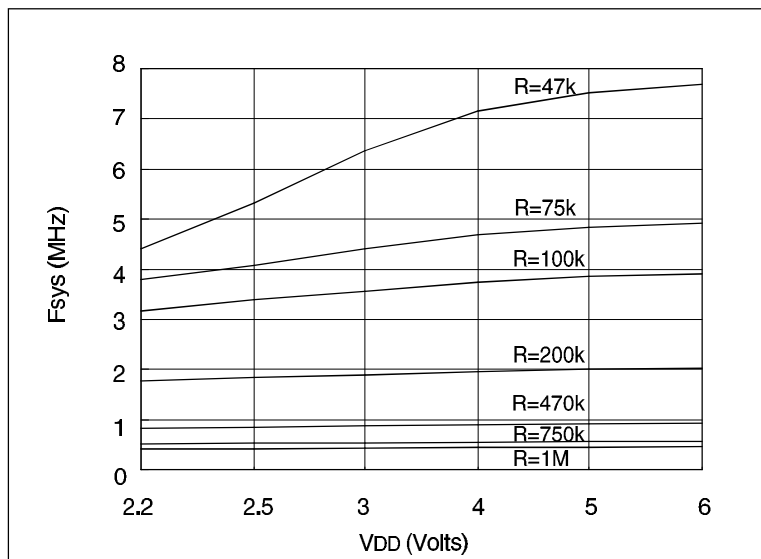


Figure C: I_{OH} vs. V_{OH} , $V_{DD}=3V$

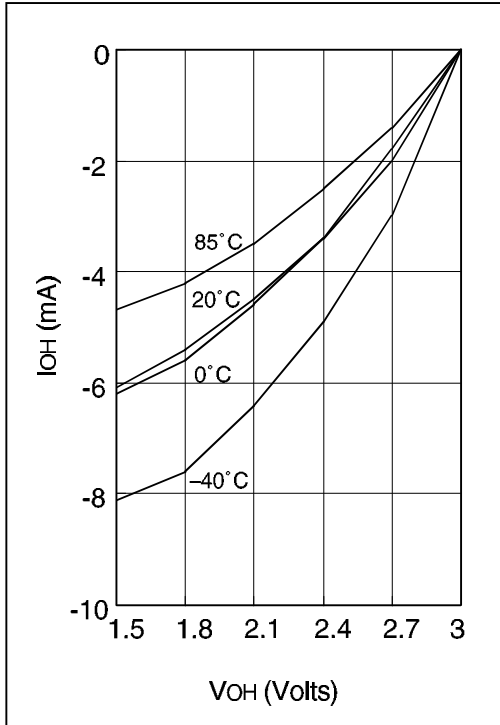


Figure D: I_{OH} vs. V_{OH} , $V_{DD}=5V$

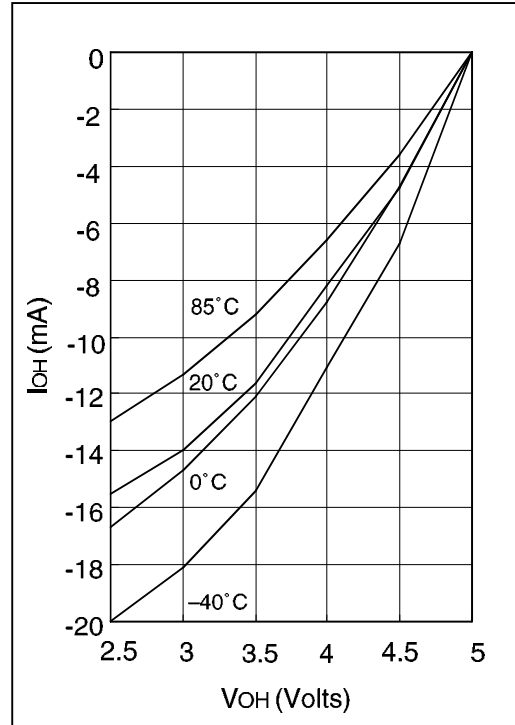


Figure E: I_{OL} vs. V_{OL} , $V_{DD}=3V$

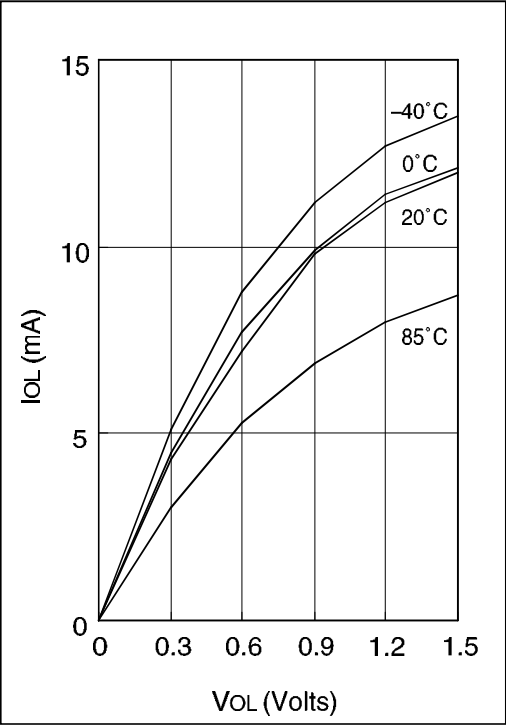


Figure F: I_{OL} vs. V_{OL} , $V_{DD}=5V$

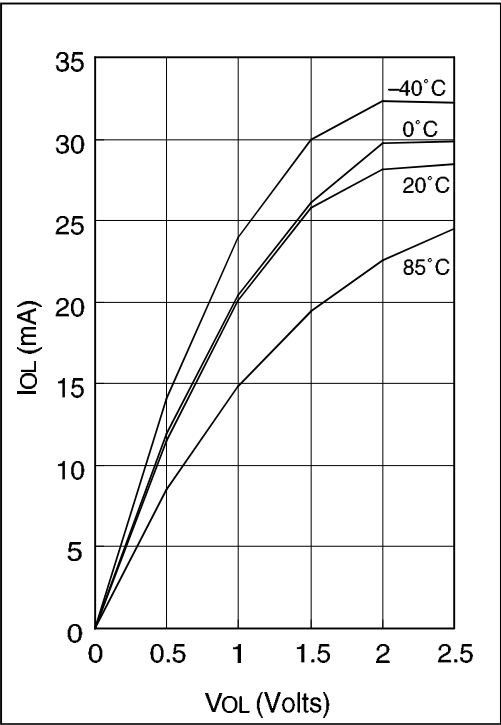


Figure G: V_{DD} vs. R_{PH} in Max.

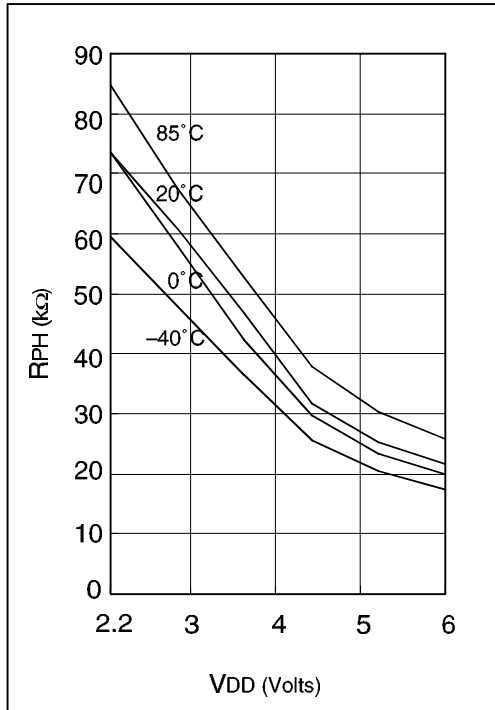
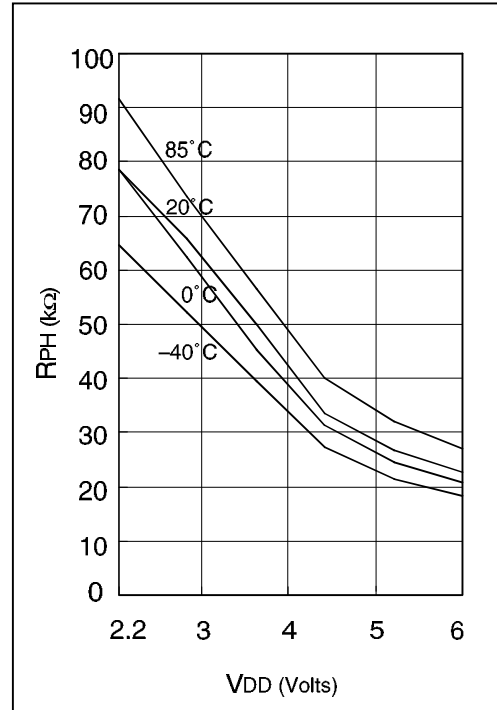


Figure H: V_{DD} vs. R_{PH} in Min.



***Note:**

$$R_{PH} = \frac{V_{DD}}{I_{RPH}}$$

I_{RPH} : Source current while forcing through the I/O port (input mode & pull-high option) to VSS.

Figure I: V_{IH} , V_{IL} vs. V_{DD} in -40°C to $+85^{\circ}\text{C}$

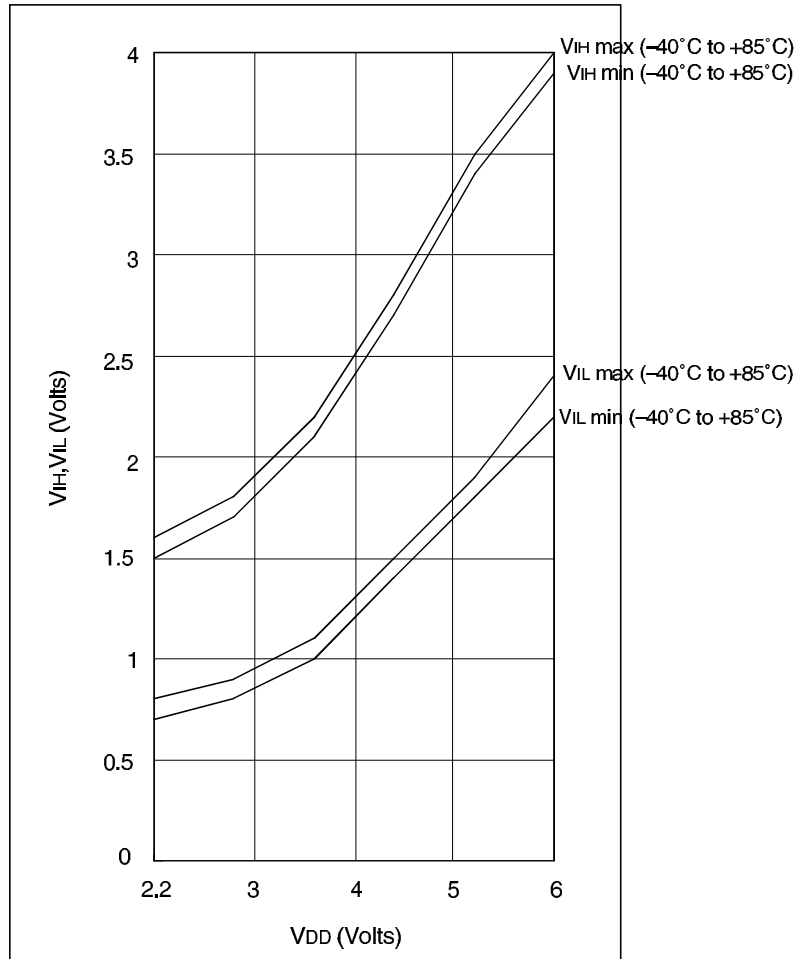


Figure J: Typical I_{STB} vs. V_{DD} watchdog enabled

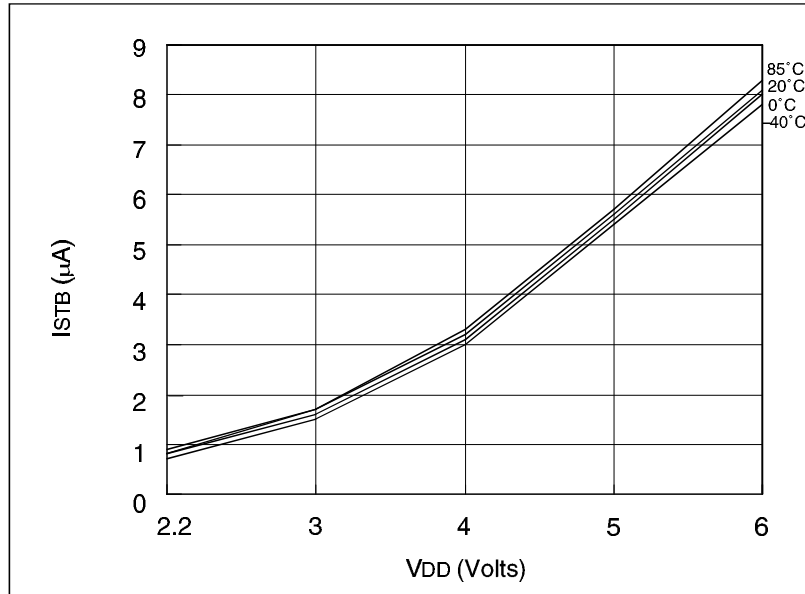


Figure K: Typical I_{STB} vs. V_{DD} watchdog disabled

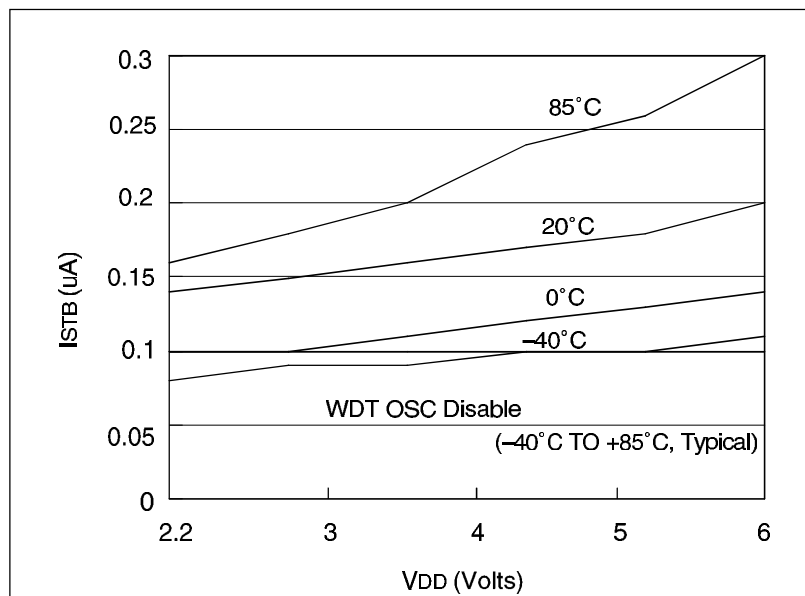
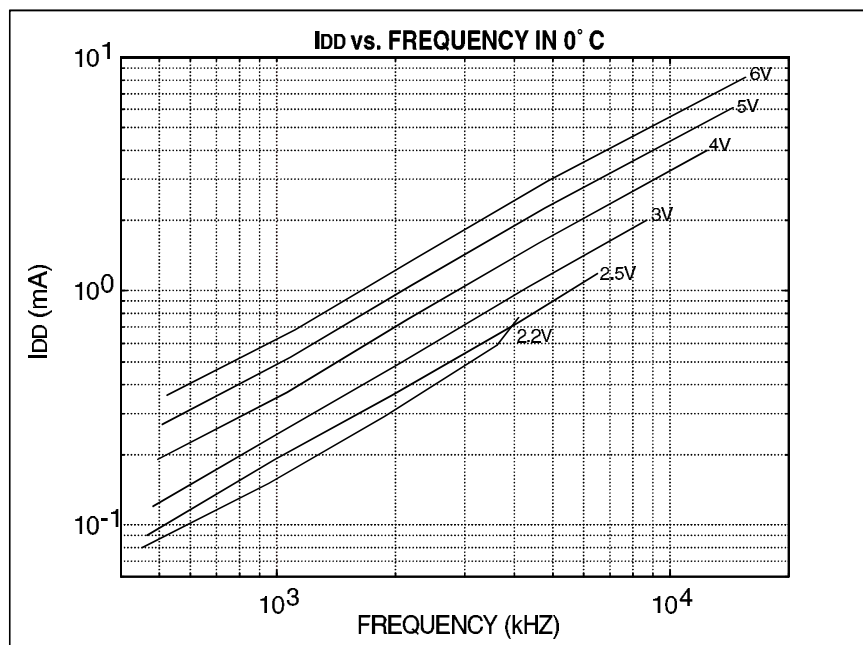
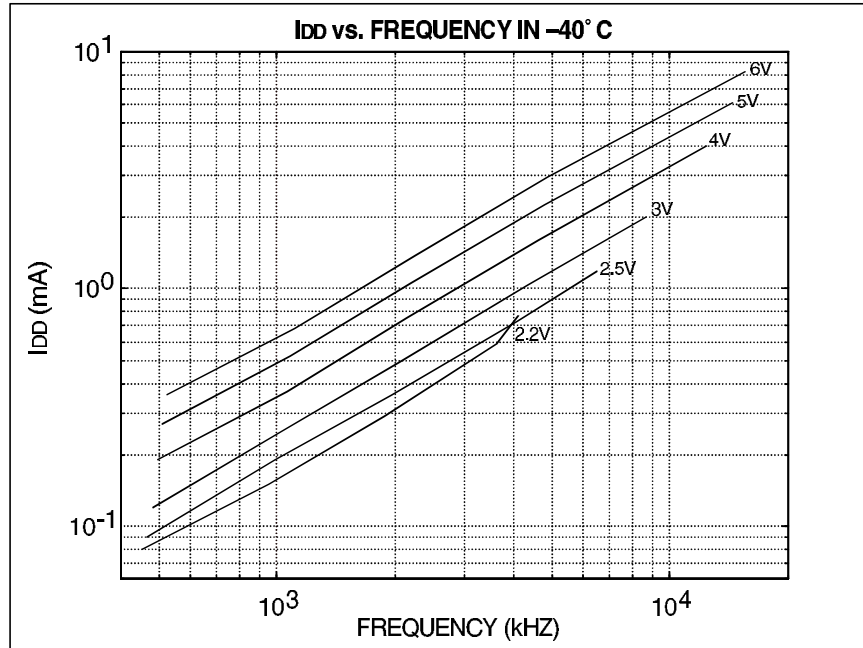


Figure L: Maximum I_{DD} vs. Frequency (external clock -40°C To 85°C)



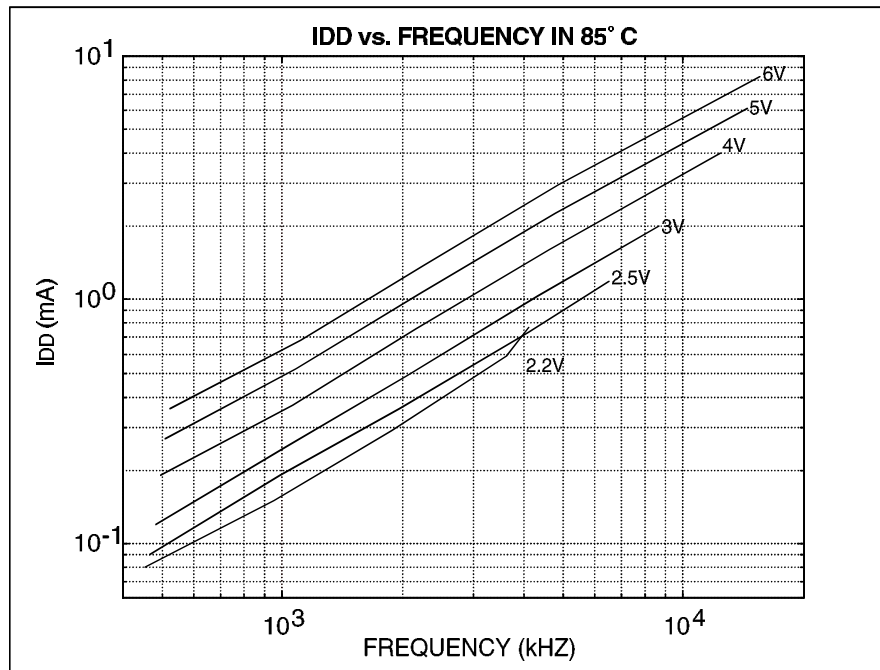
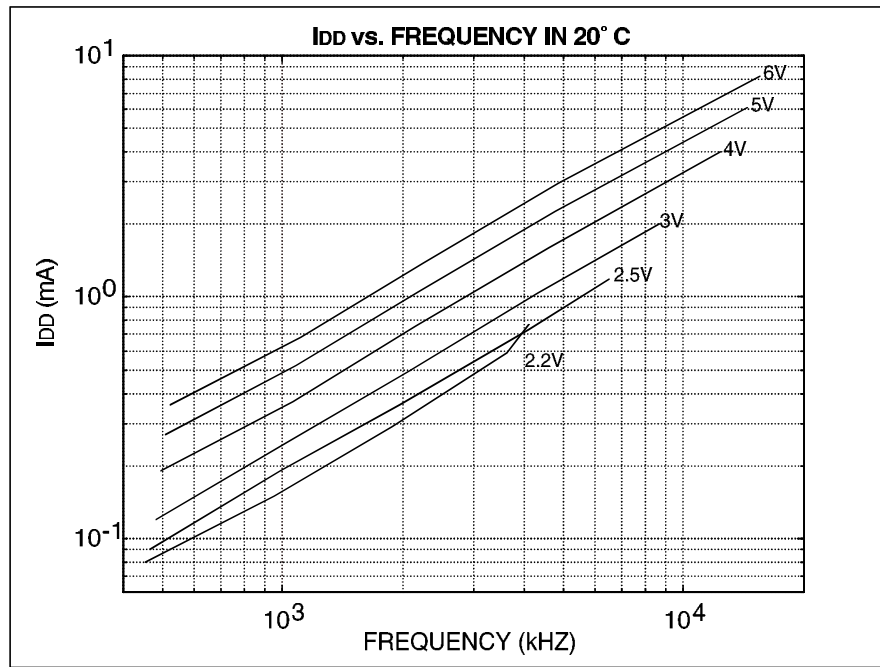


Figure M: Operating voltage-Operating frequency (crystal)

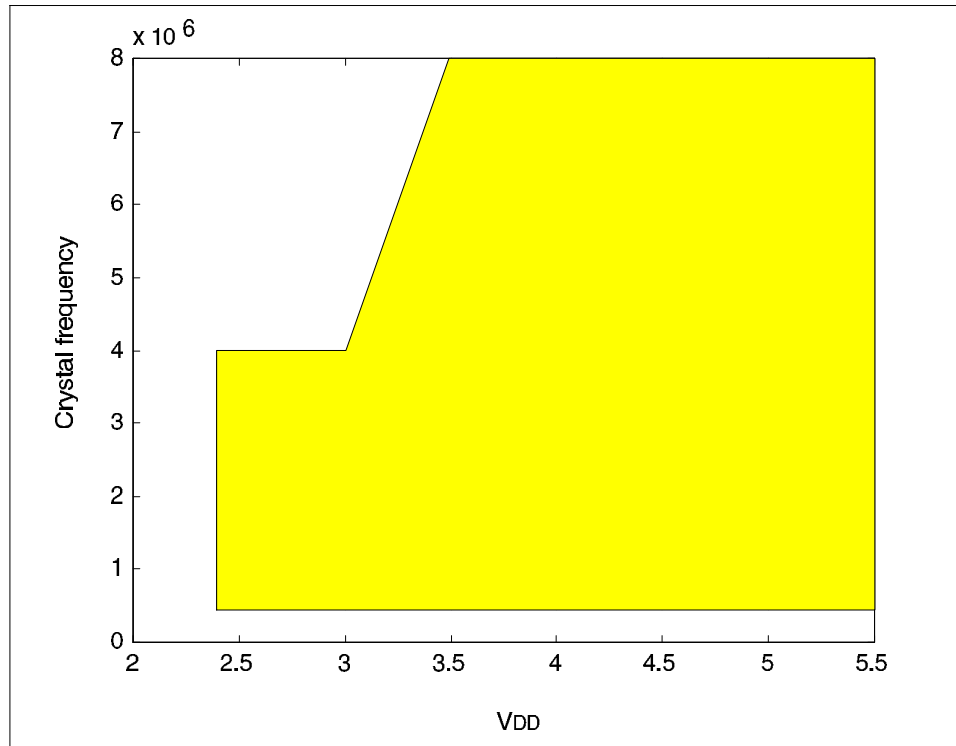
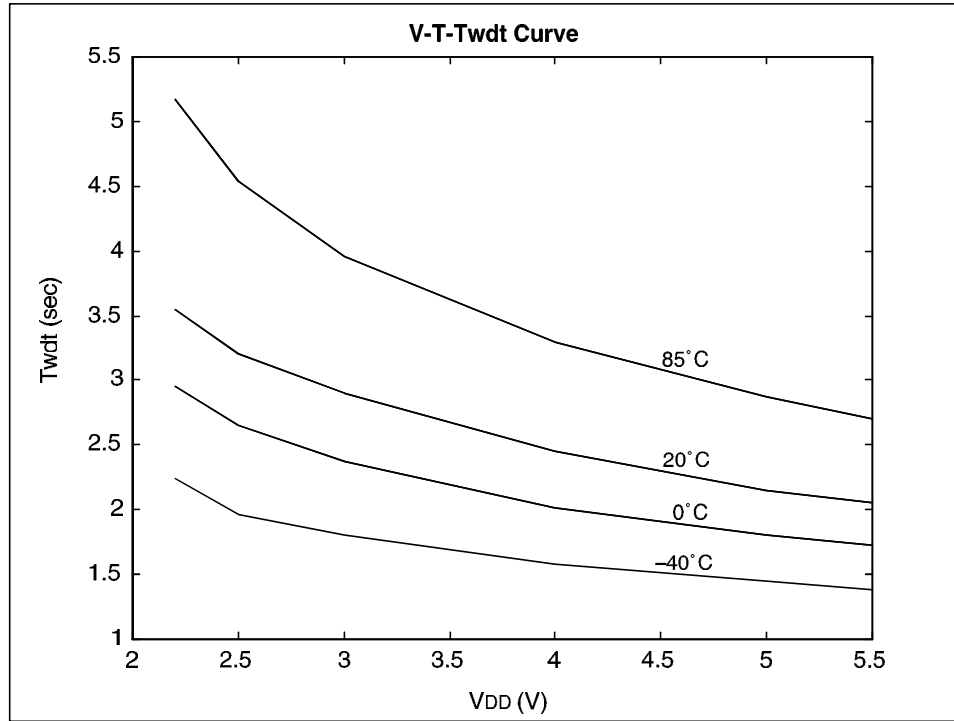


Figure N: Operating voltage vs. T_{WDT}



***Note :**

T_{WDT}: $32768 \times (\text{WDTOSC period})$